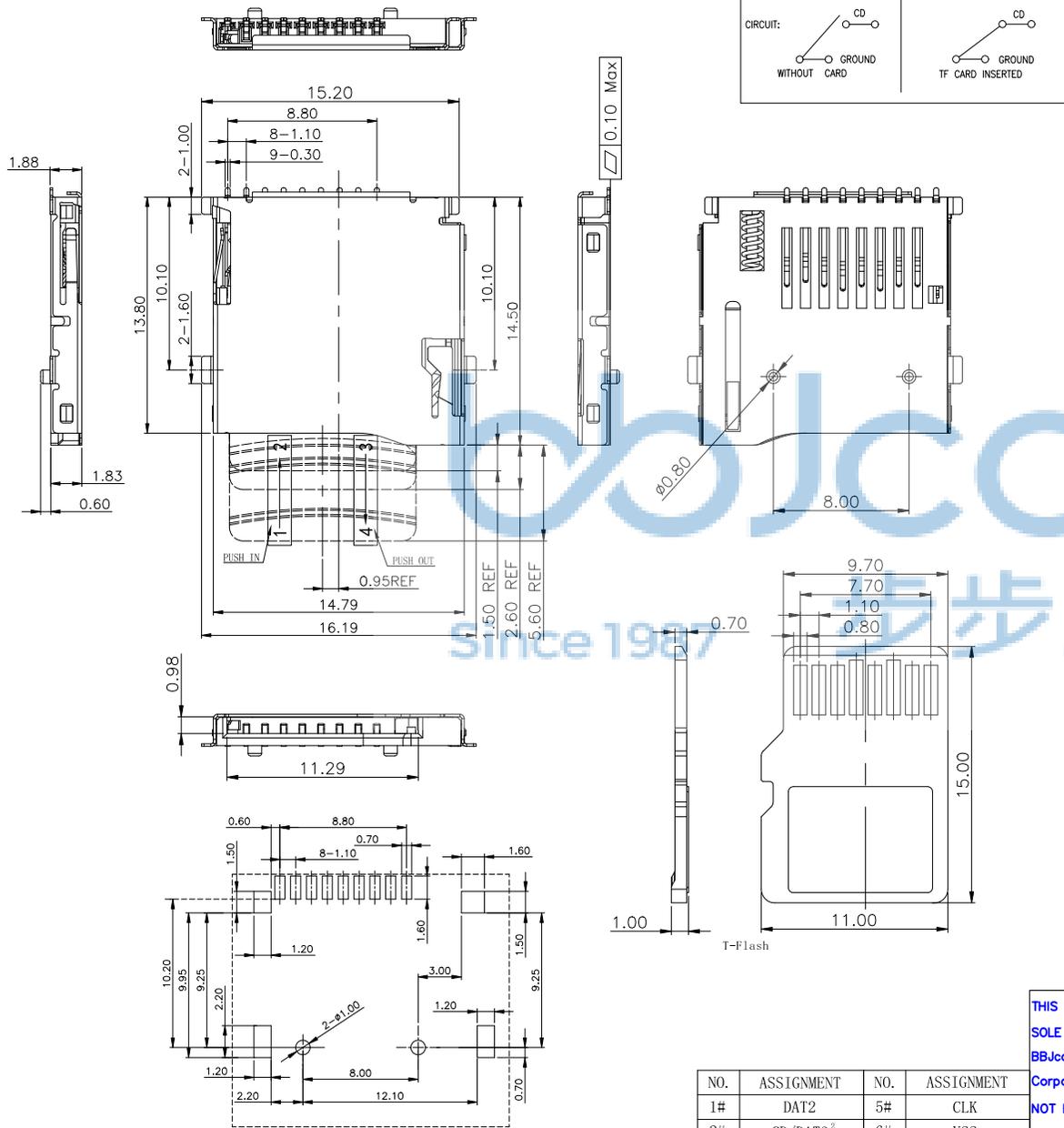
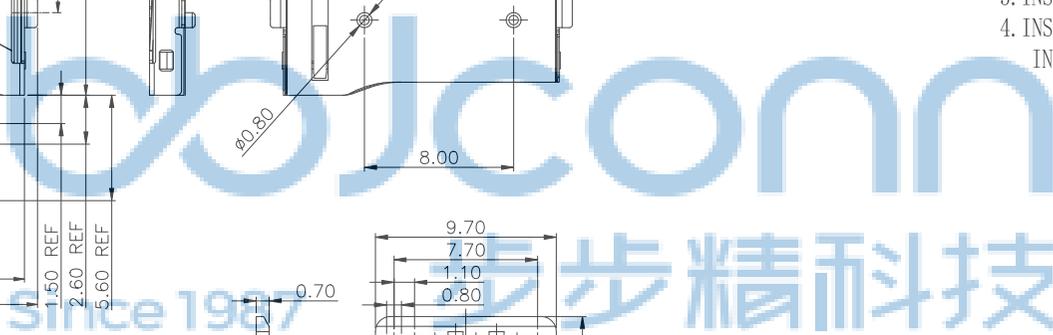


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0				



- 一、Materials and electroplating specifications:
1. shell: stainless steel;  
Plating nickel 30 u";  
Solder foot Gold plated 0.5u"
  2. terminal: phosphor copper;  
Plating nickel 30 u"  
Solder foot tin plated 80U"  
Gold-plated 0.5U in contact area.
  3. Insulator: High Temperature Thermoplastic, UL94V-0;  
Color Black.
- 二、SPECIALITY:
1. CONTACT RESISTANCE: 100mΩ Max;
  2. DIELECTRIC STRENGTH: 500V/AC 1min No Breakdown
  3. INSULATION RESISTANCE: 1000MΩ Min. 500V DC
  4. INSERTION FORCE: 0.50Kgf—1.20Kgf;  
INSERTION FORCE: 0.50Kgf—1.20Kgf;



(RECOMMENDED/P.C.B)HOLE LAYOUT  
COMPONENT SIDE VIEW TOLERANCE:±0.05

NO.	ASSIGNMENT	NO.	ASSIGNMENT
1#	DAT2	5#	CLK
2#	CD/DAT3 <sup>2</sup>	6#	VSS
3#	CMD	7#	DATO
4#	VDD	8#	DAT1
9#	CD		

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PDWG.NO: 0023-1

**深圳市步步精科技有限公司**

NAME: 卡座 TF 外焊 9Pin H=1.88 贴片 带柱 平脚镀金

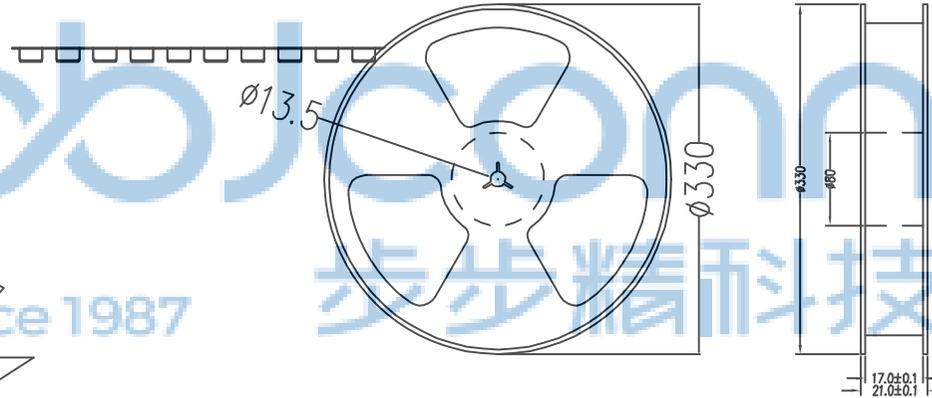
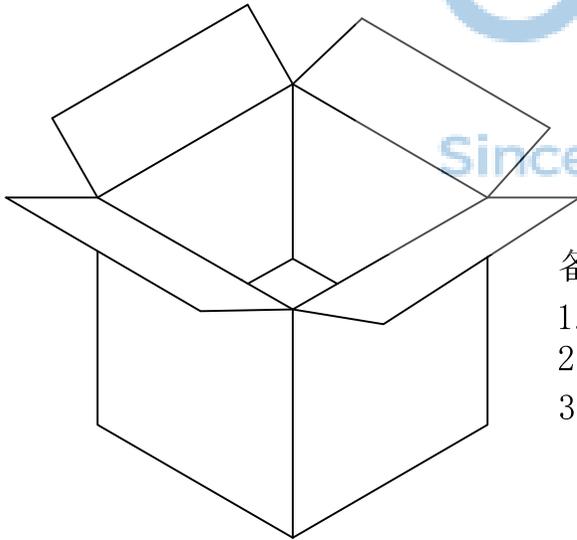
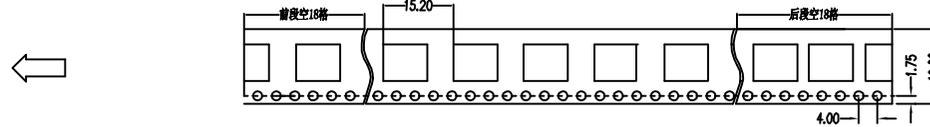
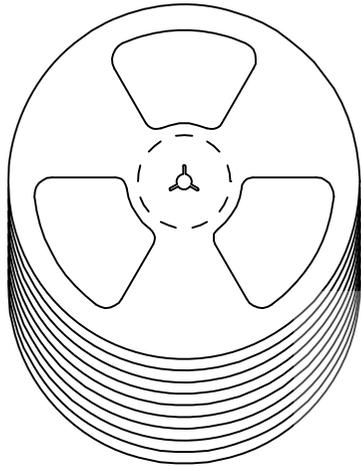
PJ. NO.: CD.01.02-01-0002

SIZE: A4 DRW NO.:

FINISH: SEE NOTES MAT'L.: SEE NOTES

SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/2

APPD.	JM_Zheng
CHKD.	TSP
DR.	LYX



备注:

1. 包装数量: 1000/PCS/卷, 10卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:  
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$   
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$   
卷盘: 聚苯乙烯。

纸箱规格: 345\*345\*23MM

纸箱规格: 345\*345\*35MM

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.X: $\pm 0.38$ .XX: $\pm 0.25$ .XXX: $\pm 0.13$ X': $\pm 3'$ X'': $\pm 2'$ XX': $\pm 1'$		NAME: 卡座 TF 外焊 9Pin H=1.88 贴片 带柱 平脚镀金	
APPD. JM_Zheng	CHKD. TSP	PJ. NO.: CD.01.02-01-0002 SIZE: A4 DRW NO.:	
PDWG.NO: 0023-1	DR. LYX	FINISH: SEE NOTES    MAT'L.: SEE NOTES SCALE: N/A    REV.: A3    UNIT: mm    PAGE: 2/2	